

Part Number: XZCBD50W-2

3.0x2.0mm RIGHT ANGLE SMD LED

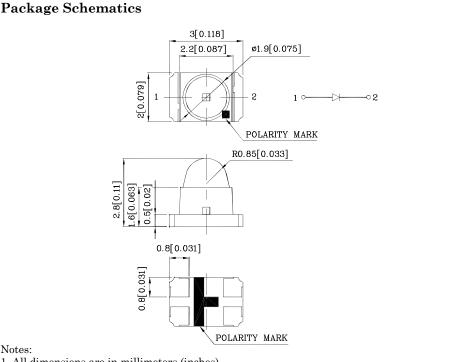
Features

- Ideal for indication light on hand held products
- Long life and robust package
- Standard Package: 2,000pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- RoHS compliant





ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES



1. All dimensions are in millimeters (inches).

Notes:

2. Tolerance is $\pm 0.2(0.008")$ unless otherwise noted.

3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		Blue (InGaN)	Unit	
Reverse Voltage	V_{R}	5	V	
Forward Current	\mathbf{I}_{F}	30 mA		
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	150	mA	
Power Dissipation	PD	120	mW	
Operating Temperature	$T_{\rm A}$	$-40 \sim +85$	°C	
Storage Temperature	Tstg	$-40 \sim +85$		
Electrostatic Discharge Threshold (HBM)		250	V	

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

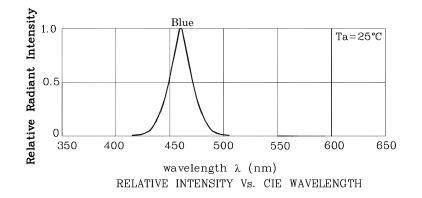
Operating Characteristics (T _A =25°C)	Blue (InGaN)	Unit	
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	3.3	V
Forward Voltage (Max.) (I _F =20mA)	V_{F}	4	V
Reverse Current (Max.) (V _R =5V)	I_R	50	uA
Wavelength of Peak Emission CIE127-2007*(Typ.) (I _F =20mA)	λP	460*	nm
Wavelength of Dominant Emission CIE127-2007*(Typ.) (I _F =20mA)	λD	465*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$ riangle\lambda$	25	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	100	pF

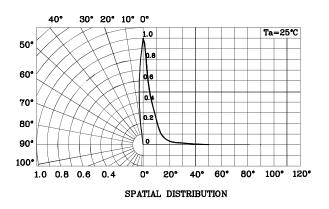
Part Number	Emitting Color	Emitting Material	Lens-color	CIE127	Intensity 7-2007* 0mA) cd	Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XZCBD50W-2	Blue	InGaN	Water Clear	300*	397*	460*	10°

*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

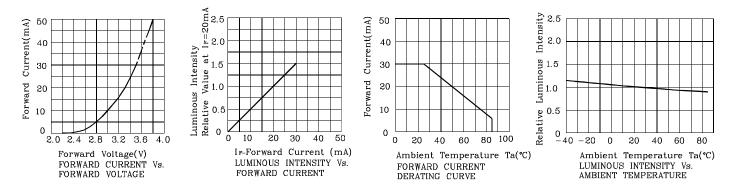
XDSB2452 V4-Z Layout: Maggie L.





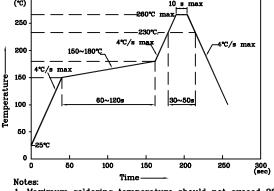


Slue



LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)



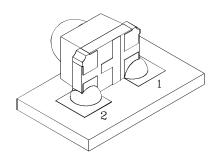
1. Maximum soldering temperature should not exceed 260°C

2. Recommended reflow temperature: 145°C-260°C 3. Do not put stress to the epoxy resin during

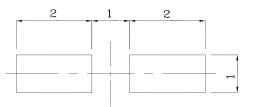
high temperatures conditions



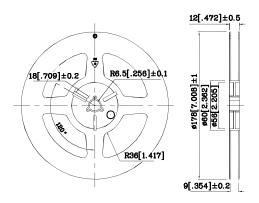
✤ The device has a single mounting surface. The device must be mounted according to the specifications.



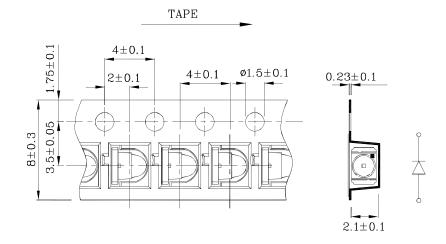
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension



Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

2. Luminous intensity / luminous flux: +/-15%

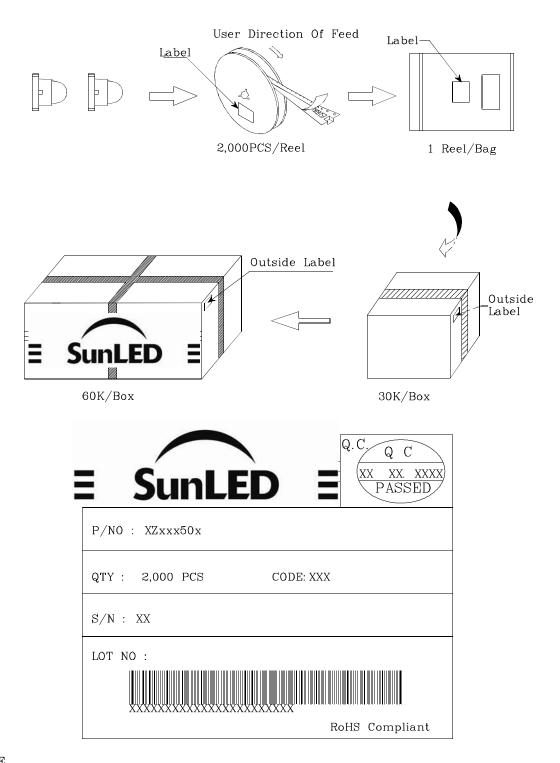
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

Sep 22,2016



PACKING & LABEL SPECIFICATIONS



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- 2. Contents within this document are subject to improvement and enhancement changes without notice.
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- 6. Additional technical notes are available at http://www.SunLEDusa.com/TechnicalNotes.asp

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